



Product Change Notification

108344 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 108344 - 00
Change Title: **Boxed Dual-Core Intel® Xeon® 5100 Series Processors (Woodcrest), PCN 108344-00, Product Material, Thermal Solution Material Change, Retail Box Artwork Change, & Label Change**
Date of Publication: **March 21, 2008**

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Apr 21, 2008
Date of First Availability of Post-Conversion Material:	Apr 21, 2008

The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

Description of Change to the Customer:

Due to thermal efficiency improvements, Intel is changing the supplied thermal solutions for mainstream products for the Boxed Dual-Core Intel® Xeon® 5100 Series Processors (Woodcrest), and will incur the following changes:

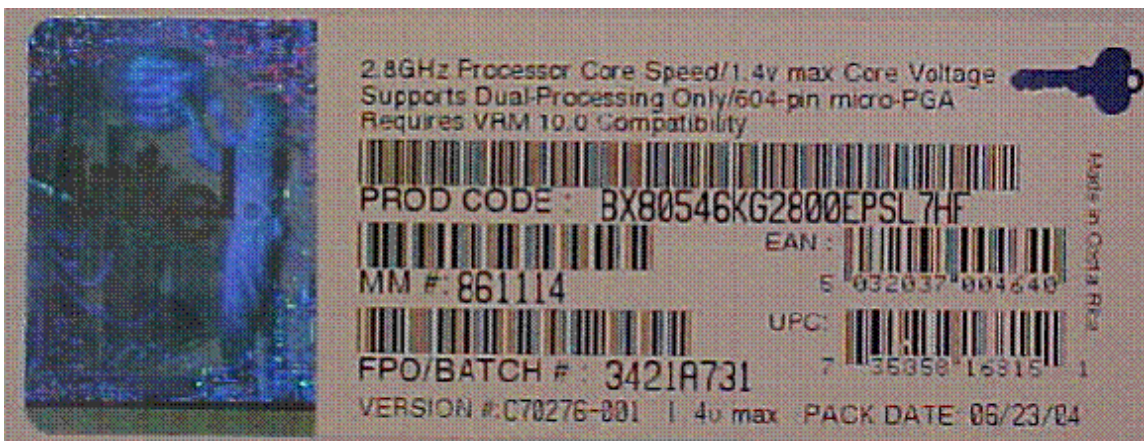
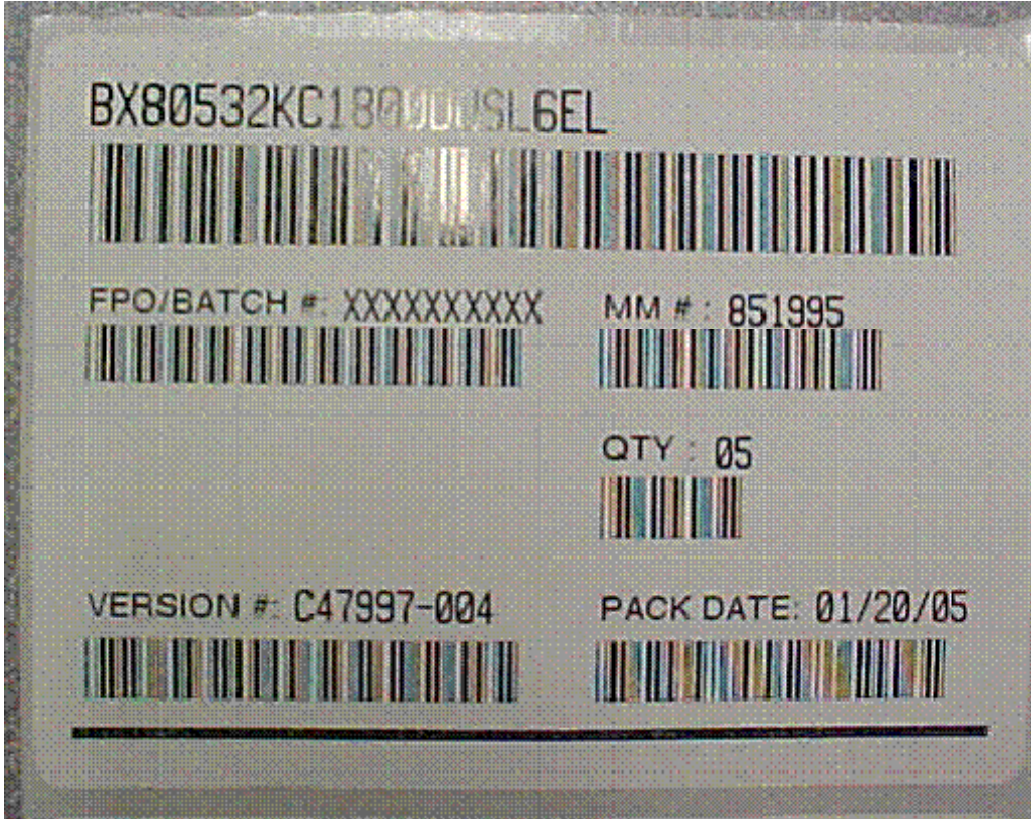
- For mainstream products (80W and lower), the LGA771-A and LGA771-C thermal solutions, which utilize a copper heat sink, will change to the LGA771-E and LGA771-F, which utilize an aluminum heat sink. The LGA771-E and LGA771-F are designed and validated to meet the processor cooling requirements of mainstream processors with TDP of 80W and lower.
- The CPU Box artwork has been updated to incorporate new pictures of the aluminum heat sink solution, and add a footnote that the thermal solution in the box may differ from the picture (for SKUs that feature the copper-based heat sink). Additional changes below:
 - Updated copyright date and legal copy to new, shorter line
 - Added Chinese ECO marks
 - Moved all English text to the back of the box, and moved the Russian to the bottom
 - Updated part numbers
 - URLs were moved to make room for the English text

Description of Change to the Customer Cont'd:

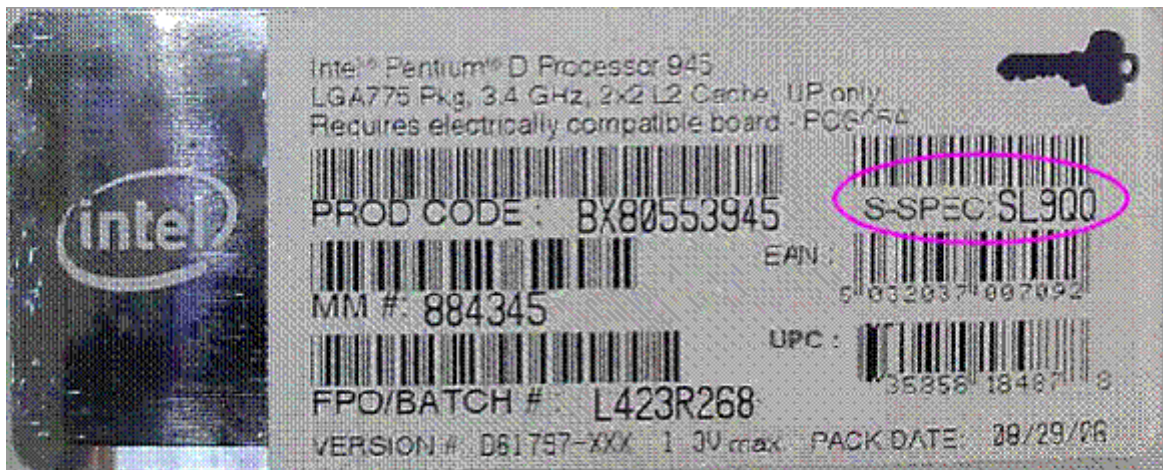
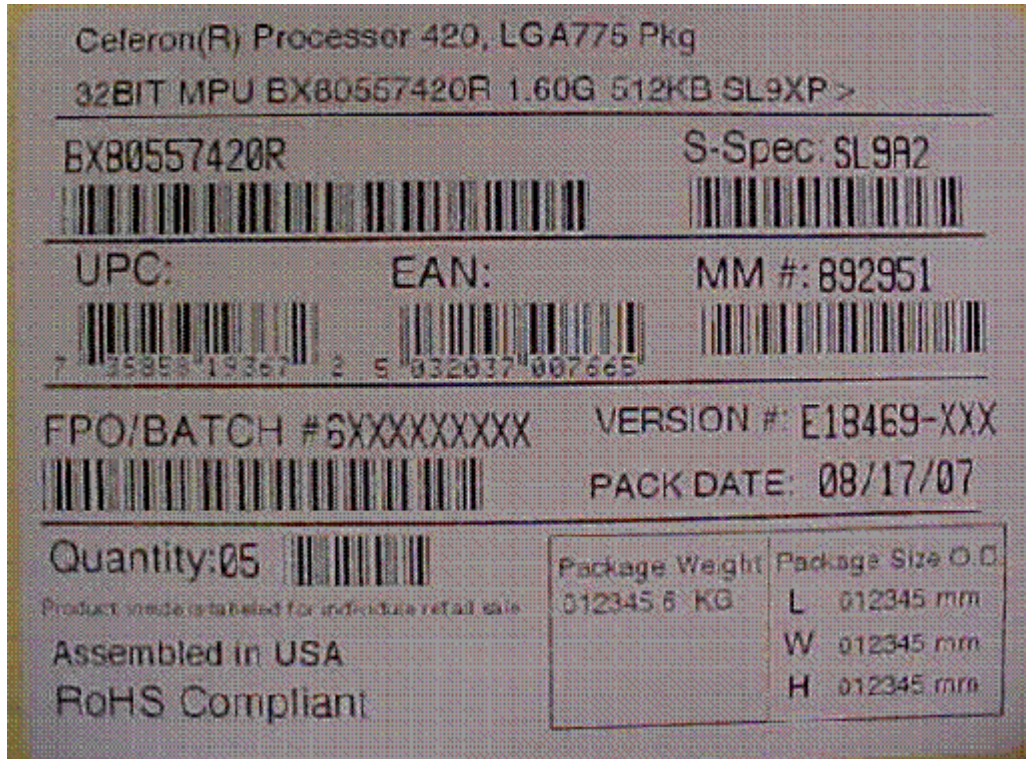
- The FPO and Disti Labels have been updated to separate the S-Spec. The Disti Label has additional fields such as Product Information (Header Text), EAN & UPC, Country of Origin, Resale Statement, and Package Weight and Dimensions. Also the Version and Pack Date barcodes have been removed.

Please note that these pictures are representative of label changes only and do not reflect the products specified in this PCN

Current:



New:



Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers.

Products Affected / Intel Ordering Codes:

Boxed Dual-Core Intel® Xeon® Processors							
Processor#	Frequency	Pre Conversion Product Code	Pre Conversion S-Spec	Pre Conversion MM#	Post Conversion Product Code	Post Conversion S-Spec	Post Conversion MM#
5148	2.33 GHZ	BX805565148A	S LABH	890798	BX805565148A	S LAG4	892145
5148	2.33 GHZ	BX805565148P	S LABH	890799	BX805565148P	S LAG4	892146

Reference Documents / Attachments:

Document:

Location #:

PCN Revision History:

Date of Revision:

Revision Number:

Reason:

March 21, 2008

00

Originally Published PCN